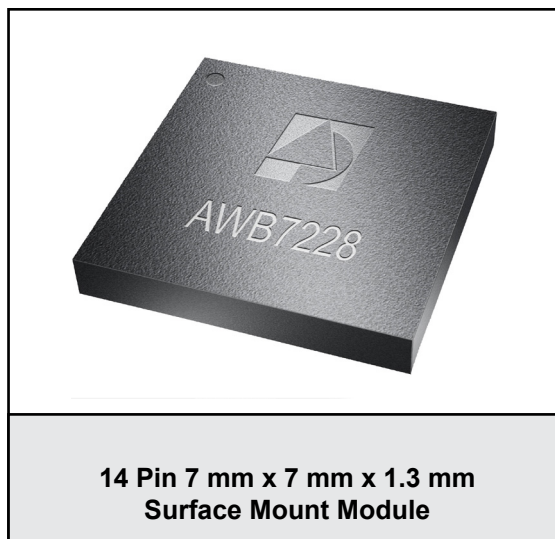


FEATURES

- InGaP HBT Technology
- -47 dBc ACPR @ ± 10 MHz, +27 dBm
- 27 dB Gain
- High Efficiency
- Low Transistor Junction Temperature
- Matched for a 50 Ω System
- Low Profile Miniature Surface Mount Package; RoHS Compliant
- Multi-Carrier Capability

APPLICATIONS

- LTE, WCDMA and HSDPA Air Interfaces
- FDD and TDD Systems
- Picocell, Femtocell, Home Nodes
- Customer Premises Equipment (CPE)
- Data Cards and Terminals



PRODUCT DESCRIPTION

The AWB7228 is a fully matched, Multi-Chip-Module (MCM) designed for picocell, femtocell, and customer premises equipment (CPE) applications. Its high linearity and efficiency meet the extremely demanding needs of small cell infrastructure architectures. Designed for LTE, WCDMA and HSDPA air interfaces operating in the 2.545 GHz to 2.69 GHz band, the AWB7228 delivers up to +27 dBm of LTE (E-TM1.1) power with an ACPR of -47 dBc. It operates from

a convenient +4.5 V supply and provides 27 dB of gain. The device is manufactured using an advanced InGaP HBT MMIC technology offering state-of-the-art reliability, temperature stability, and ruggedness. The self-contained 7 mm x 7 mm x 1.3 mm surface mount package incorporates RF matching networks optimized for output power, efficiency, and linearity in a 50 Ω system.

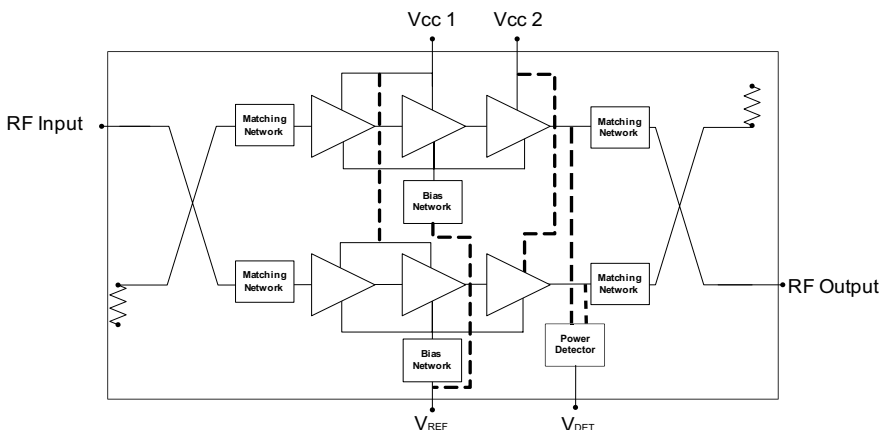


Figure 1: Block Diagram

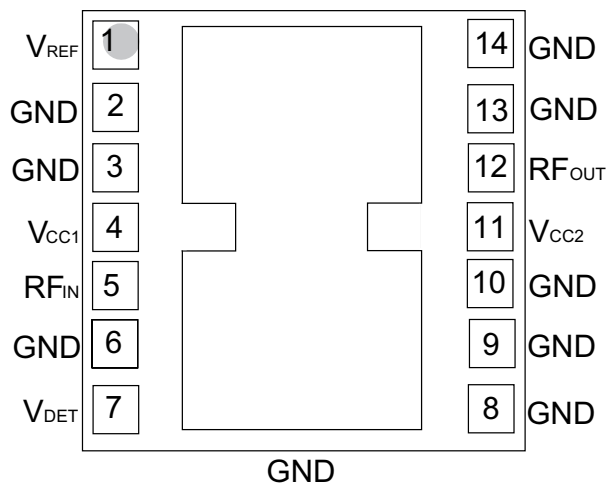


Figure 2: Pinout (X-ray Top View)

Table 1: Pin Description

PIN	NAME	DESCRIPTION
1	V_{REF}	Reference Voltage
2	GND	Ground
3	GND	Ground
4	V_{CC1}	Supply Voltage
5	RF_{IN}	RF Input
6	GND	Ground
7	V_{DET}	Detector Voltage
8	GND	Ground
9	GND	Ground
10	GND	Ground
11	V_{CC2}	Supply Voltage
12	RF_{OUT}	RF Output
13	GND	Ground
14	GND	Ground

ELECTRICAL CHARACTERISTICS

Table 2: Absolute Minimum and Maximum Ratings

PARAMETER	MIN	MAX	UNIT
Supply Voltage (V_{CC})	0	+5	V
Reference Voltage (V_{REF})	0	+3.5	V
RF Output Power (P_{OUT})	-	+30	dBm
ESD Rating			
Human Body Model ⁽¹⁾	Class 1C	-	
Charged Device Model ⁽²⁾	Class IV	-	
MSL Rating ⁽³⁾	4	-	
Junction Temperature (T_J)	-	+150	°C
Storage Temperature (T_{STG})	-40	+150	°C

Stresses in excess of the absolute ratings may cause permanent damage. Functional operation is not implied under these conditions. Exposure to absolute ratings for extended periods of time may adversely affect reliability.

Notes:

(1) JEDEC JS-001-2010.

(2) JEDEC JESD22-C101D.

(3) 260 °C peak reflow.

Table 3: Operating Ranges

PARAMETER	MIN	TYP	MAX	UNIT	COMMENTS
Operating Frequency (f)	2545	-	2690	MHz	
Supply Voltage (V_{CC})	+3.6	+4.5	+4.65	V	
Reference Voltage (V_{REF})	+2.75 0	+2.85 -	+2.95 +0.5	V	PA "on" PA "shut down"
RF Output Power (P_{OUT})	-	+27	-	dBm	
Case Temperature (T_C)	-40	-	+85	°C	

The device may be operated safely over these conditions; however, parametric performance is guaranteed only over the conditions defined in the electrical specifications.

Table 4: Electrical Specifications
(T_C = +25 °C, V_{CC} = +4.5 V, V_{REF} = +2.85 V, 50 Ω system)

PARAMETER	MIN	TYP	MAX	UNIT	COMMENTS
Gain ⁽²⁾	25	27	32	dB	
ACPR ^{(1), (2), (3)} @ 10 MHz @ 20 MHz	- -	-47 -60	-45 -53	dBc	
Power-Added Efficiency ^{(1), (2), (3)}	12	14	-	%	
Thermal Resistance (R _{JC}) ⁽⁴⁾	-	12.5	-	°C/W	Junction to Case
Supply Current ^{(1), (2), (3)}	-	795	-	mA	total through V _{CC} pins
Quiescent Current (I _{cq})	200	275	330	mA	
Reference Current	12	14	19	mA	through V _{REF} pin
Leakage Current	-	3	10	μA	V _{CC} = +4.65 V, V _{REF} = 0 V
Harmonics 2f _o 3f _o , 4f _o	- -	-40 -55	-30 -50	dBc	
Input Return Loss	12	18	-	dB	
Output Return Loss	12	18	-	dBm	
RF Switching Time ⁽⁵⁾ Rise Time (PA “off” to “on”) Fall Time (PA “on” to “off”)	- -	- -	12 4	μs	V _{CC} = +4.5 V, V _{REF} switched between 0 V and +2.85 V
Spurious Output Level (all spurious outputs)	-	-	-60	dBc	P _{OUT} ≤ +27 dBm In-band load VSWR < 5:1 Out-of-band load VSWR < 10:1 Applies over all voltage and temperature operating ranges
Load mismatch stress with no permanent degradation or failure	8:1	-	-	VSWR	V _{CC} = +4.5 V, P _{OUT} = +27 dBm Applies over full operating temperature range

Notes:

(1) Measured at 2620 MHz.

(2) P_{OUT} = +27 dBm.

(3) E-TM1.1 LTE 10 MHz BW.

(4) Use only V_{CC2} (pin 11) current when calculating device junction temperature.

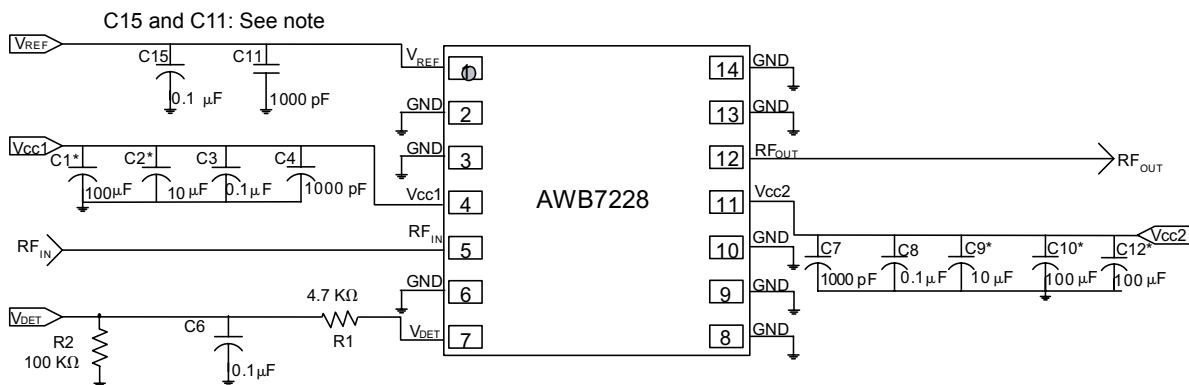
(5) Rise Time defined from time at which V_{REF} is switched from 0 V to +2.85 V, to time at which the RF output power achieves 90% of the average steady-state “on” level; Fall Time defined from time at which V_{REF} is switched from +2.85 V to 0 V, to time at which the RF output power decreases to 10% of the average steady-state “on” level.

APPLICATION INFORMATION

To ensure proper performance, refer to all related Application Notes on the ANADIGICS web site:
<http://www.anadigics.com>

Shutdown Mode

The power amplifier may be placed in a shutdown mode by applying logic low levels (see Operating Ranges table) to the V_{REF} voltage.

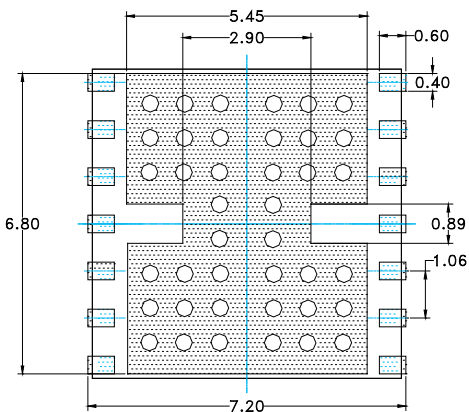


* Optional

Note:

To achieve the RF Switching Time specifications listed in Table 4 the maximum recommended capacitance on the V_{REF} line is $0.01 \mu\text{F}$. The noise on the V_{REF} line should be kept as low as possible to minimize required capacitance.

Figure 3: Application Circuit Schematic

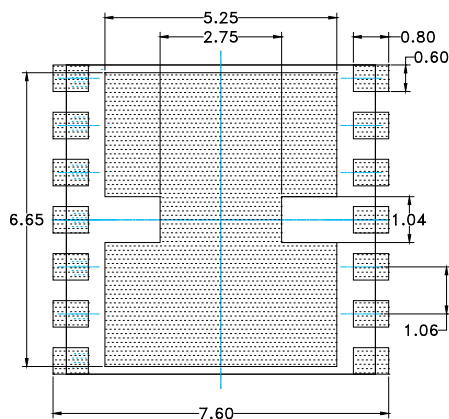


PCB METAL
TOP (X-RAY) VIEW

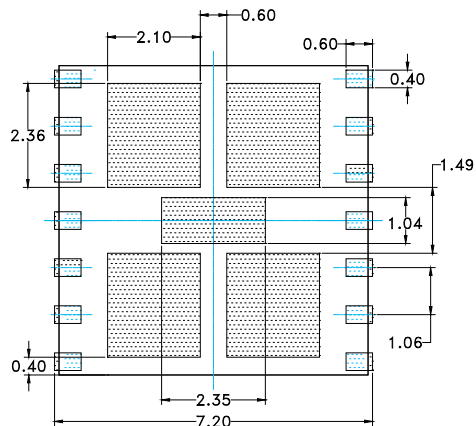
ONLY PACKAGE I/O's AND
GROUND REQUIREMENTS
SHOWN.

NOTES:

- (1) UNLESS SPECIFIED DIMENSIONS ARE SYMMETRICAL ABOUT CENTER LINES SHOWN.
- (2) DIMENSIONS IN MILLIMETERS.
- (3) VIAS SHOWN IN PCB METAL VIEW ARE FOR REFERENCE ONLY. NUMBER & SIZE OF THERMAL VIAS REQUIRED DEPENDENT ON HEAT DISSIPATION REQUIREMENT AND THE PCB PROCESS CAPABILITY.



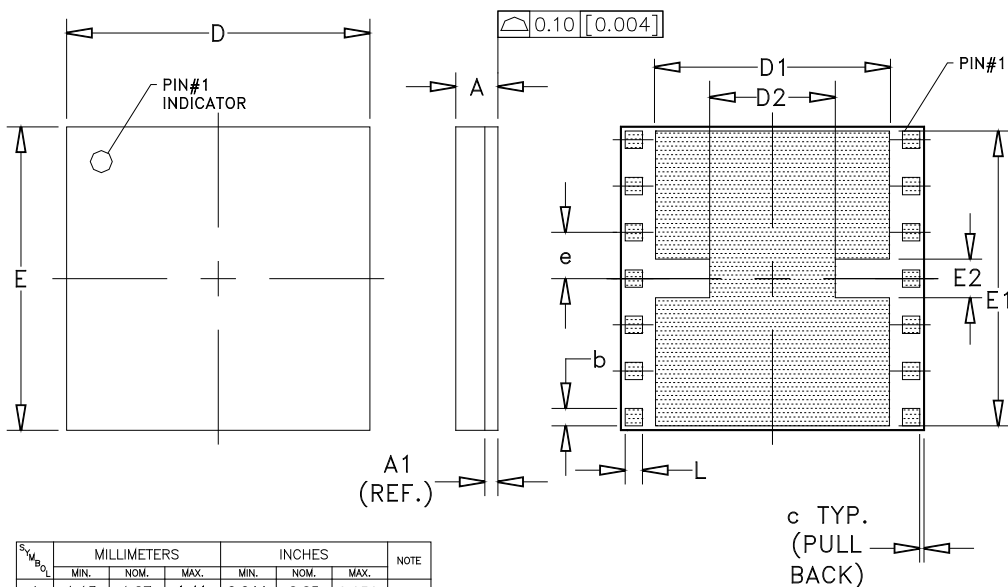
PCB SOLDER MASK
TOP (X-RAY) VIEW



STENCIL APERTURE
TOP (X-RAY) VIEW

Figure 4: PCB Footprint

PACKAGE OUTLINE



NOTES:

1. CONTROLLING DIMENSIONS: MILLIMETERS
2. UNLESS SPECIFIED TOLERANCE=±0.076[0.003].
3. PADS (INCLUDING CENTER) SHOWN
UNIFORM SIZE FOR REFERENCE ONLY.
ACTUAL PAD SIZE AND LOCATION WILL
VARY WITHIN MIN. AND MAX. DIMENSIONS
ACCORDING TO SPECIFIC LAMINATE DESIGN.

Figure 5: Package Outline - 14 Pin 7 mm x 7 mm x 1.3 mm Surface Mount Module

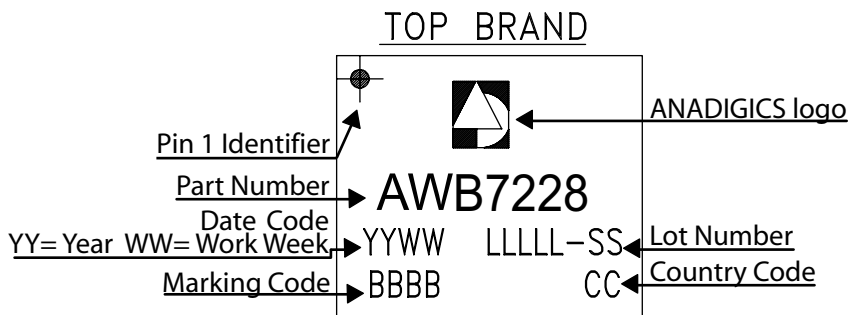


Figure 6: Branding Specification



Table 5: Tape & Reel Dimensions

PACKAGE TYPE	TAPE WIDTH	POCKET PITCH	REEL CAPACITY	MAX REEL DIA
7 mm x 7 mm x 1.3 mm	16 mm	12 mm	2500	13"

ORDER NUMBER	TEMPERATURE RANGE	PACKAGE DESCRIPTION	COMPONENT PACKAGING
AWB7228P8	-40 °C to +85 °C	RoHS-compliant 14 Pin 7 mm x 7 mm x 1.3 mm Surface Mount Module	Tape and Reel, 2500 pieces per Reel

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URL: <http://www.anadigics.com>**IMPORTANT NOTICE**

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